

RoHs/WEEE-Compliant SOIC-to-JEDEC TO Adapter

FEATURES

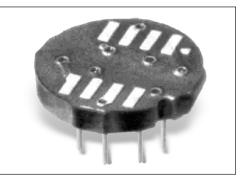
- Pb-Free RoHs/WEEE-compliant
- 8-position SOIC footprint on the top and a circular, 8-pin JEDEC TO can male pin footprint on the bottom. ICs now available only in 8-position SOIC packages can be readily mounted on boards having JEDEC TO thru-hole footprints without having to redesign the board.
- Consult factory for mounting of consigned chips.

GENERAL SPECIFICATIONS

- ADAPTER BOARD: 0.062 [1.58] thick FR-4 or IS410 per IPC 4101A/26 with 1-oz. Cu traces, both sides
- MALE PINS: Brass 360 1/2-hard per UNS C36000, ASTM B16/B16M
- MALE PIN PLATING: 10µ [0.254µ] min. Au per MIL-G-45204 over 100µ [2.54µ] Ni per SAE AMS-QQ-N-290
- OPERATING TEMPERATURE: 221°F [105°C]

MOUNTING CONSIDERATIONS

• SUGGESTED PCB HOLE SIZE: 0.028 ±0.003 [0.71 ±0.08] dia.



CUSTOMIZATION: In addition to the standard products shown on this page, Aries specializes in custom design and production. Special materials, platings, sizes, and configurations can be furnished, depending on the quantity. **NOTE:** Aries reserves the right to change product general specifications without notice.

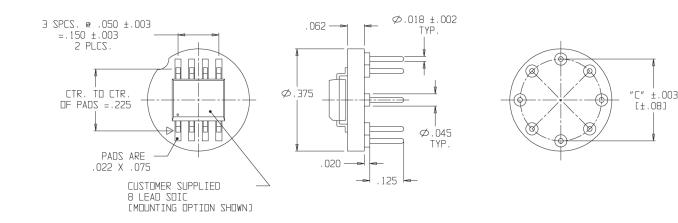
ORDERING INFORMATION

P/N	Dim "C"
1109814-RC	0.200 [5.08]

ALL DIMENSIONS: INCHES [MILLIMETERS]

ALL TOLERANCES: ±0.005 [0.13] UNLESS OTHERWISE SPECIFIED DIP-to-TO ADAPTER ALSO AVAILABLE. CONSULT DATA SHEET 18012

CONSULT FACTORY FOR OTHER SIZES AND CONFIGURATIONS





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